

# MATERIAL DECLARATION SHEET



Material Number	CDSOT563-0502			
Product Line	Semiconductor Products			
Compliance Date	2013/8/6			
RoHS Compliant	Yes	MSL	3	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Wafer	Silicon	0.000131	Silicon	7440-21-3	100.00%	3.309%	3.309%
2	Lead frame	Copper Alloy	0.000003	Manganese	7439-96-5	0.30%	0.083%	27.734%
			0.000104	Nickel	7440-02-0	9.50%	2.635%	
			0.000007	Iron	7439-89-6	0.60%	0.166%	
			0.000025	Tin	7440-31-5	2.30%	0.638%	
			0.000005	Zinc	7440-66-6	0.50%	0.139%	
			0.000001	Lead	7439-92-1	0.05%	0.014%	
			0.000952	Copper	7440-50-8	86.74%	24.057%	
			0.000000	Silver	7740-22-4	0.01%	0.003%	
3	Epoxy	Polymer	0.000175	Si-oxide Quartz	14808-60-7	50.00%	4.420%	8.841%
			0.000096	Epoxy resin	Proprietary	27.50%	2.431%	
			0.000009	Aromatic Amine	Proprietary	2.50%	0.221%	
			0.000070	Epoxy resin modifier	Proprietary	20.00%	1.768%	

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4	Wire	Noble metal	0.000152	Aurum	7440-57-5	99.99%	3.839%	3.8394%
			0.00000002	other	/	0.01%	0.0004%	
5	Mold Compound	Polymer	0.001737	Silica	60676-86-0	80.00%	43.8696%	54.8376%
			0.000217	Epoxy Resin	Trade Secret	10.00%	5.484%	
			0.000211	Phenolic Resin	Trade Secret	9.70%	5.319%	
			0.000007	Carbon Black	1333-86-4	0.30%	0.165%	
6	Plating	Plating	0.000057	Tin	7440-31-5	99.90%	1.438%	1.439%
			0.00000006	Others	/	0.1%	0.001%	
		Total weight	<b>0.003959 g</b>					

**This Document was updated on: 2013/8/6**

**Important remarks:**

1. It is the responsibility of the user to verify they are accessing the latest version.